

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT8055103

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT	
<b>NATURE OF CONVEYANCE:</b>	RELEASE OF SECURITY INTEREST	
<b>CONVEYING PARTY DATA</b>		
	<b>Name</b>	<b>Execution Date</b>
	MONTAGE CAPITAL II, L.P.	07/12/2023
<b>RECEIVING PARTY DATA</b>		
<b>Name:</b>	BASELINE, INC.	
<b>Street Address:</b>	10259 WEST EMERALD STREET, SUITE 160	
<b>City:</b>	BOISE	
<b>State/Country:</b>	IDAHO	
<b>Postal Code:</b>	83704	
<b>PROPERTY NUMBERS Total: 5</b>		
<b>Property Type</b>	<b>Number</b>	
<b>Patent Number:</b>	7292049	
<b>Patent Number:</b>	7756917	
<b>Patent Number:</b>	6798215	
<b>Application Number:</b>	16533535	
<b>Application Number:</b>	16533544	
<b>CORRESPONDENCE DATA</b>		
<b>Fax Number:</b>	(650)644-0520	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
<b>Phone:</b>	6506483802	
<b>Email:</b>	PATTY@PATTYCHENG.COM	
<b>Correspondent Name:</b>	PATTY CHENG	
<b>Address Line 1:</b>	2625 MIDDLEFIELD RD., #215	
<b>Address Line 4:</b>	PALO ALTO, CALIFORNIA 94306	
<b>NAME OF SUBMITTER:</b>	PATTY CHENG	
<b>SIGNATURE:</b>	/s/ Patty Cheng	
<b>DATE SIGNED:</b>	07/13/2023	
<b>Total Attachments: 2</b>		
source=Baseline_-_IP_Release#page1.tif		
source=Baseline_-_IP_Release#page2.tif		

## RELEASE OF SECURITY INTEREST

This Release of Security Interest is made as of July 12, 2023, by Montage Capital II, L.P. ("Lender"), in favor of Baseline, Inc., an Idaho corporation ("Company"), with its principal place of business located at 10259 West Emerald Street, Suite 160, Boise, ID 83704.

### Recitals

WHEREAS, Company granted to Lender a security interest in the intellectual property of Company, including without limitation the patent items listed on Exhibit A attached hereto (collectively, the "Intellectual Property"), under an Intellectual Property Security Agreement dated as of May 17, 2019 and as amended from time to time (the "Security Agreement") which was recorded with the US Patent and Trademark Office.

WHEREAS, Company has no outstanding obligations to Lender under the terms of the Security Agreement, Lender agrees to release its security interest in the Intellectual Property.

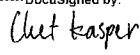
### Agreement

NOW THEREFORE, Lender hereby agrees that the Security Agreement is terminated and Lender terminates and releases its security interest in the Intellectual Property and reassigns to Company, without warranty or recourse, all interest of Lender in the Intellectual Property.

In the event that any signature hereto is executed and delivered by e-mail delivery of a ".pdf" format data file or electronic signature complying with the U.S. federal E-SIGN Act of 2000, such signature shall create a valid and binding obligation of the party executing (or on whose behalf such signature is executed) with the same force and effect as if such ".pdf" or electronic signature page were an original hereof.

LENDER:

Montage Capital II, L.P.

DocuSigned by:  
  
By 748A9866FD5847F...  
Name: Chet Kasper  
Title: Principal

**EXHIBIT A****PATENTS**

<b>Title</b>	<b>Application Number / Patent Number</b>	<b>Application Date / Issue Date</b>
System and method for detecting the dielectric constant of conductive material	7,292,049	November 6, 2007
Two wire communication apparatus and method	7,756,917	July 13, 2010
System and method for measuring moisture content in a conductive environment	6,798,215	Sept. 28, 2004
Systems, methods, and apparatuses for adaptive irrigation zone control using pressure, time, flow, and predicted behavior	16/533535	08/06/2019
Systems, methods, and apparatuses for real-time hydraulic infrastructure status and operation using logical pipe representation	16/533544	08/06/2019